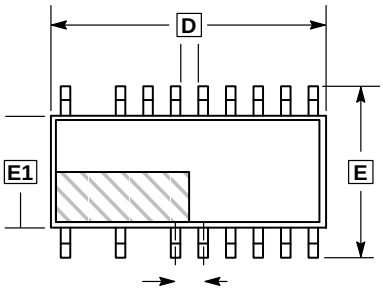
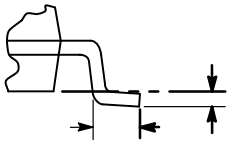
SOIC20 NB LESS PINS 2, 4 & 19
CASE 751BS
ISSUE O

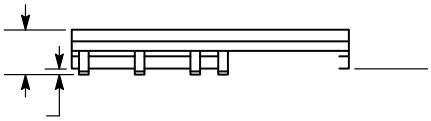
DATE 28 APR 2011

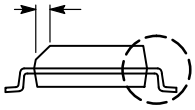
SCALE 1:1





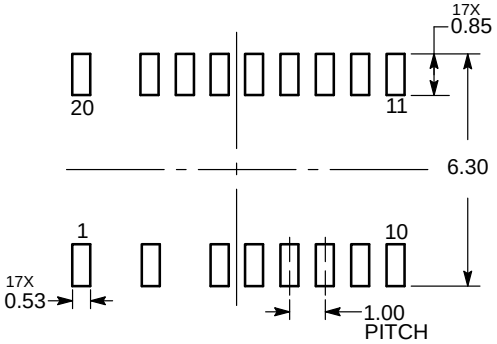
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 TOTAL IN EXCESS OF THE b DIMENSION. DIMENSION b APPLIES TO THE FLAT PORTION OF THE LEAD AND SHALL BE MEASURED BETWEEN 0.13 AND 0.25 FROM THE TIP.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS BUT DO INCLUDE MOLD MISMATCH. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. CHAMFER FEATURE IS OPTIONAL. IF NOT PRESENT, THEN A PIN ONE IDENTIFIER MUST BE LOCATED IN THIS AREA.





E	6.00 BSC
E1	3.90 BSC
e	1.00 BSC
L2	0.25 BSC

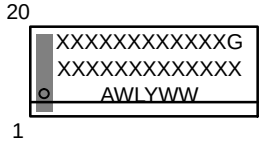
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.